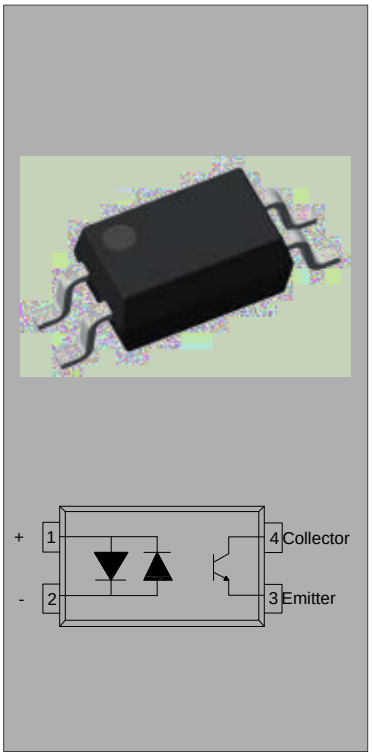
JOCT214Xt-S4 Series

Rev.A.1.0

The products are transistor opto-couplers in a SSOP4 package. The device is a photoelectric coupler composed of light-emitting diode and phototransistor. The products are widely used in switching power supply, intelligent meter, industrial control, measuring instruments, office equipment such as copiers, household appliances: such as air conditioners, fans, water heaters,etc.



High isolation 3750 VRMS
Operating temperature range -55°C to 125°C
RoHS & REACH Compliance
HBM: H3A; MM: M4; CDM:C3
CQC approved
VDE approved
UL approved

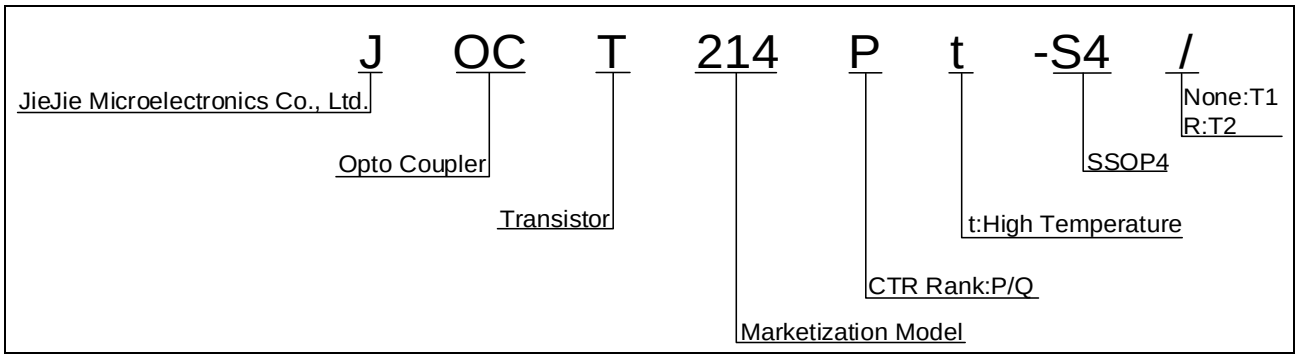
(Temperature=25°C)

Parameter		Symbol	Value	Unit
Input	Forward Current	I_F	±50	mA
	Peak Forward Current	I_{FP}	1	A
	Power Dissipation	P_D	75	mW
Output	Collector-emitter Voltage	V_{CEO}	80	V
	Emitter-collector Voltage	V_{ECO}	7	V
	Collector Current	I_C	50	mA
	Power Dissipation	P_C	150	mW
Total Power Dissipation		P_{tot}	225	mW
Isolation Voltage		V_{iso}	3750	Vrms
Operating Temperature		T_{opr}	-55~+125	
Junction Temperature		T_j	135	
Storage Temperature		T_{stg}	-55~+125	
Soldering Temperature		T_{sol}	260	

1 μs pulse AC for 1minute, R.H.=40~60%

25°C)

Condition	Min.	Typ.	Max.	Unit
I_F=±10mA	-	1.2	1.5	V
V=0, f=1MHz	-	30	250	pF
V_{CE}=20V, I_F=0	-	-	50	nA
I_C=0.1mA I_F=0	80	-	-	V
I_E=0.1mA I_F=0	7	-	-	V
I_F=±5mA V_{CE}=5V	100	-	400	%
I_F=±10mA I_C= 1mA	-	0.07	0.2	V
DC500V 40~60%R.H.	5×10^{10}	10^{11}	-	Ω
V=0, f=1MHz	-	0.3	1	pF
V_{CE}=5V, I_C=2mA R_L=100Ω, -3dB	-	80	-	kHz
V_{CE}=2V, I_C=2mA R_L=100Ω	-	4	18	μs
	-	3	18	μs
	-	9	25	μs
	-	5	25	μs



None/R	3000 Units/Reel

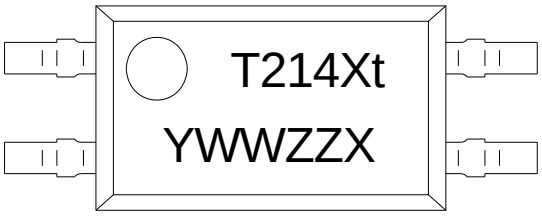


FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

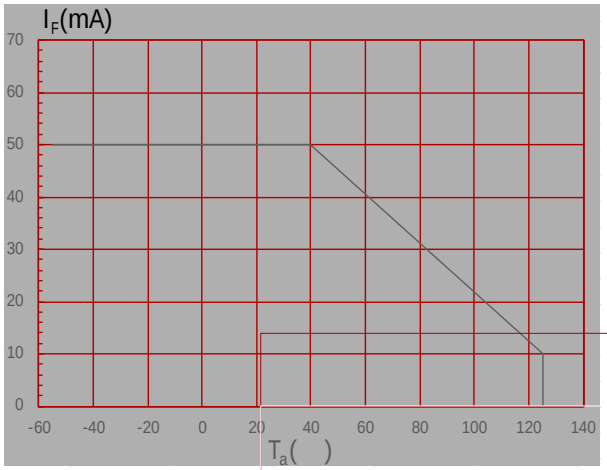


FIG.2: Collector Power Dissiption vs. Ambient Temperature

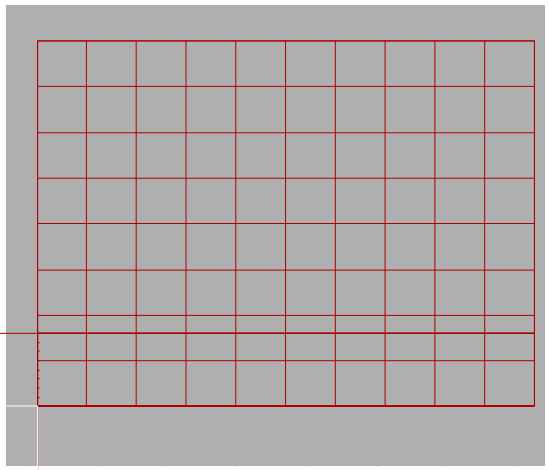


FIG.7: Normalized Current Transfer Ratio vs. Ambient Temperature

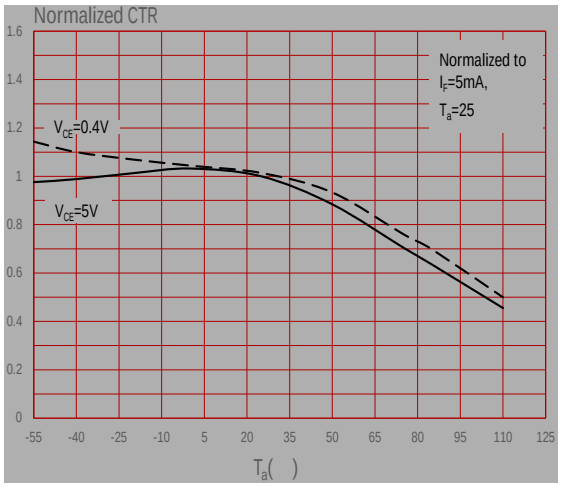


FIG.8: Normalized Collector-emitter Saturation Voltage vs. Ambient Temperature

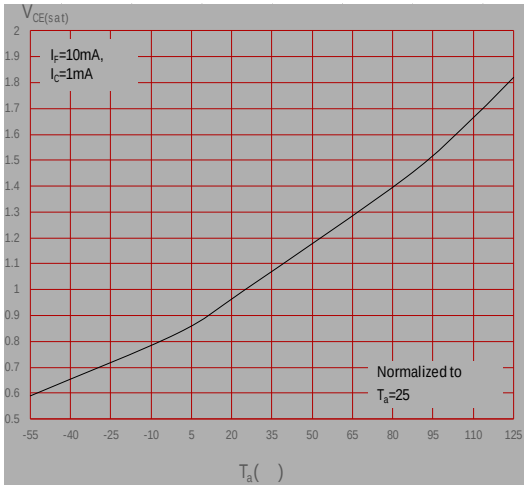


FIG.9: Response Time vs. Load Resistance

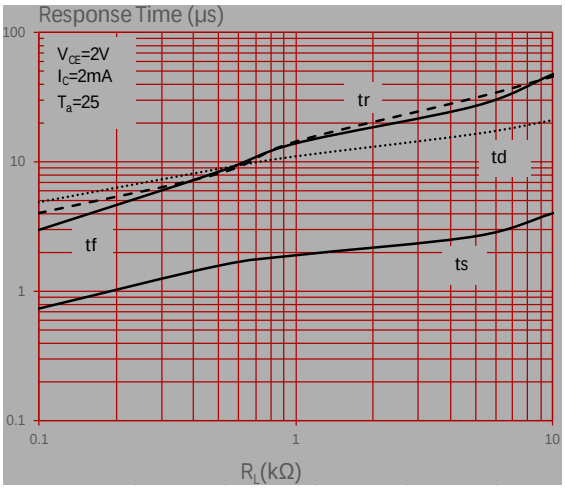
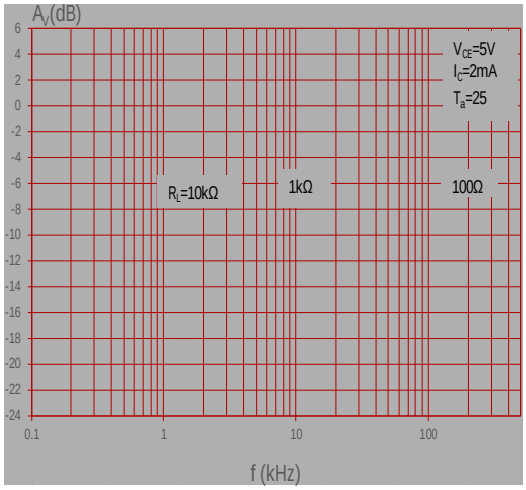
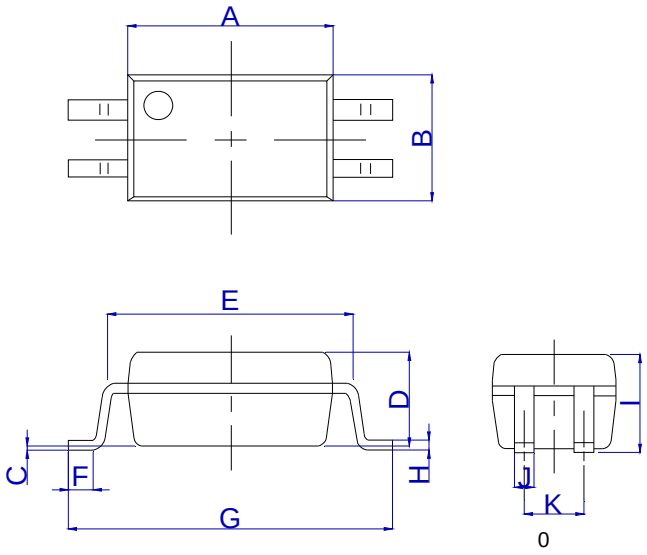


FIG.10: Frequency Response





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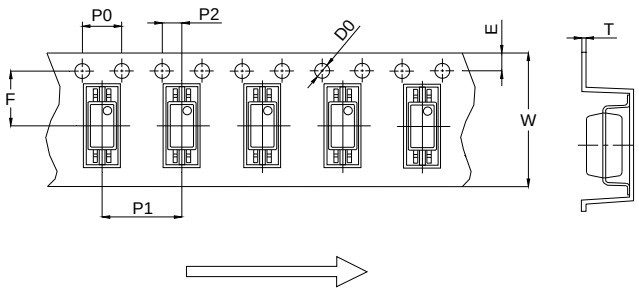
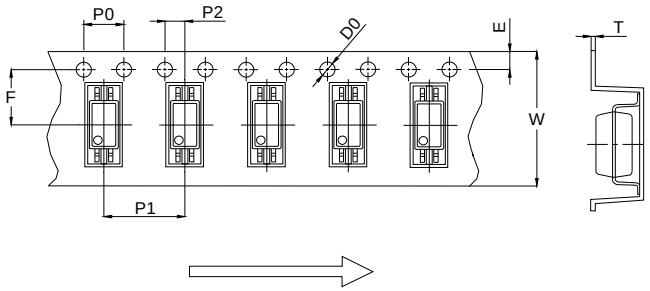
Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A						
B						
C						
D						
E						
F	0.39			0.015		
G						
H						
I	1.888					
J						



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0		1.50	1.60		0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
E	1.65	1.75	1.85	0.065	0.069	0.073
F	5.40	5.50	5.60	0.213	0.217	0.220
T	0.20	0.25	0.30	0.008	0.010	0.012
W	11.90	12.10	12.30	0.469	0.476	0.484



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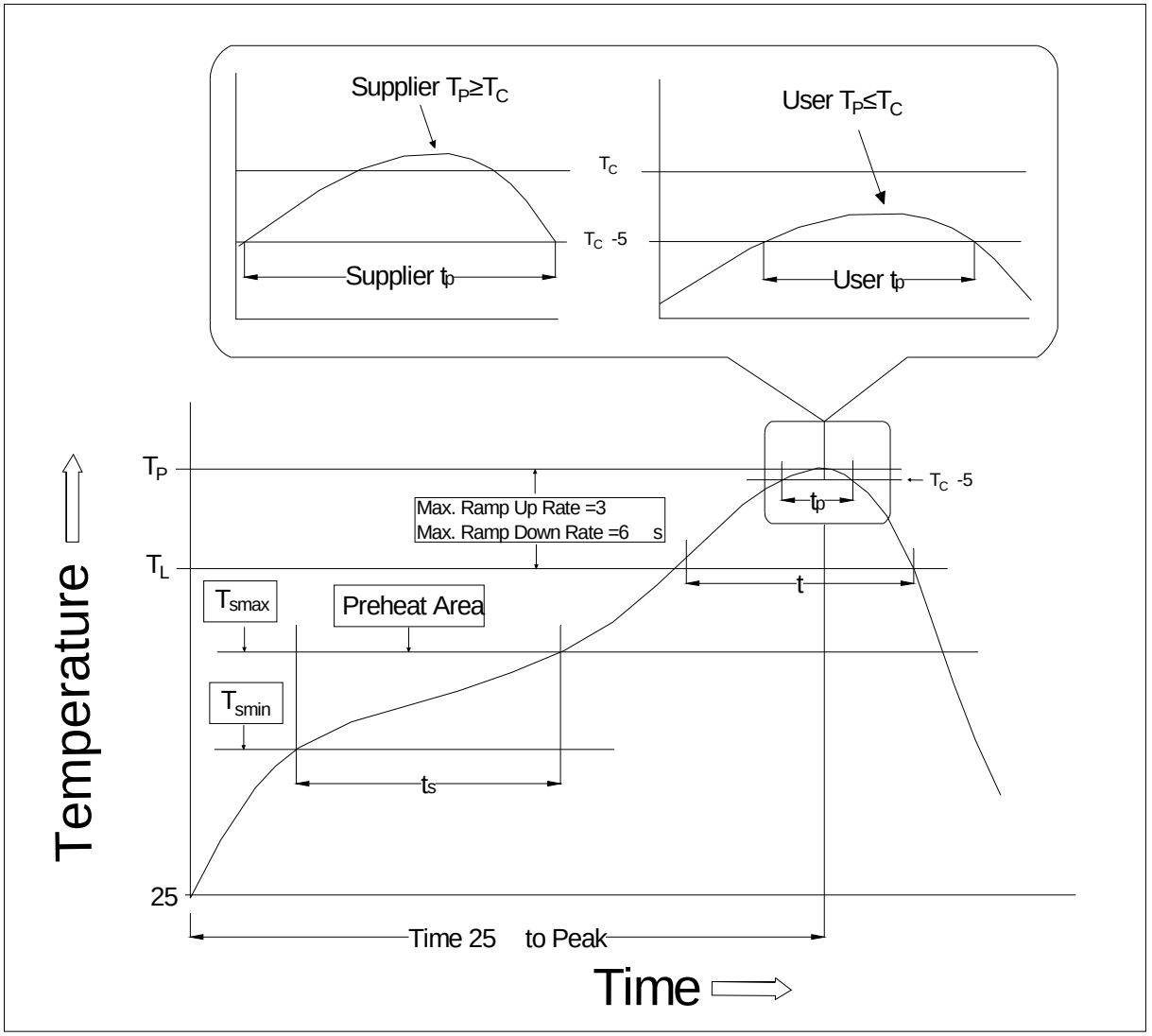

Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	100	150
Temperature Max. (Tsmax)	150	200
Time (ts) from (Tsmin to Tsmax)	60-120 seconds	60-120 seconds
Ramp-up Rate (tL to tP)	3 /second max.	3 /second max.
Liquidus Temperature (TL)	183	217
Time (tL) Maintained Above (TL)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5
Time (tP) within 5 of 260	20 seconds	30 seconds
Ramp-down Rate (TP to TL)	6 /second max.	6 /second max.
Time 25 to Peak Temperature	6 minutes max.	8 minutes max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1